MSDS Report

Report NO.: MG00001000038

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJB3R9SN10B
Package Type :	TO-263-2L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Si	si	7440-21-3	100.000%	0.330%
Lead Frame	P	7723-14-0	0.030%	61.692%
	Fe	7439-89-6	0.100%	
	Cu	7440-50-8	99.700%	
	Ag	7440-22-4	0.170%	
Die Attach	Lead	7439-92-1	93.500%	1.059%
	Tin	7440-31-5	5.000%	
	Silver	7440-22-4	1.500%	
Wire1	Al	7429-90-5	99.990%	1.129%
	others	/	0.010%	
Wire2	Cu	7440-50-8	99.990%	0.003%
	others	/	0.010%	
Mold Compound	Epoxy Resin A	Trade Secret	3.500%	34.375%
	Epoxy Resin B	Trade Secret	3.500%	
	Phenol Resin	Trade Secret	3.500%	
	Silica(Amorphous) A	60676-86-0	85.000%	
	Silica(Amorphous) B	7631-86-9	4.000%	
	Carbon Black	1333-86-4	0.500%	
Plating	Sn	7440-31-5	99.990%	1.412%
	others	/	0.010%	